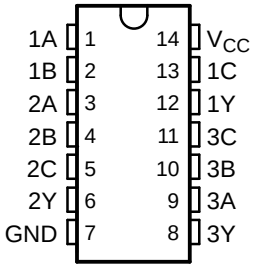
# SN74ALVC10
# TRIPLE 3-INPUT POSITIVE-NAND GATE

SCES106H–JULY 1997–REVISED OCTOBER 2004

## FEATURES

- **Operates From 1.65 V to 3.6 V**
- **Max $t_{pd}$ of 3 ns at 3.3 V**
- **±24-mA Output Drive at 3.3 V**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**
- **ESD Protection Exceeds JESD 22**
  - **– 2000-V Human-Body Model (A114-A)**
  - **– 200-V Machine Model (A115-A)**
  - **– 1000-V Charged-Device Model (C101)**

**D, DGV, NS, OR PW PACKAGE**
**(TOP VIEW)**




## DESCRIPTION/ORDERING INFORMATION

This triple 3-input positive-NAND gate is designed for 1.65-V to 3.6-V $V_{CC}$ operation.

The SN74ALVC10 performs the Boolean function $Y = \overline{A \bullet B \bullet C}$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

**ORDERING INFORMATION**

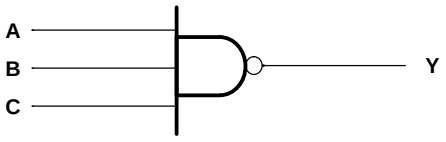
| $T_A$ | PACKAGE(1) | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---|---|---|---|---|
| -40°C to 85°C | SOIC - D | Tube | SN74ALVC10D | ALVC10 |
| | | Tape and reel | SN74ALVC10DR | |
| | SOP - NS | Tape and reel | SN74ALVC10NSR | ALVC10 |
| | TSSOP - PW | Tape and reel | SN74ALVC10PWR | VA10 |
| | TVSOP - DGV | Tape and reel | SN74ALVC10DGVR | VA10 |

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

**FUNCTION TABLE**
**(each gate)**

| INPUTS | | | OUTPUT |
|---|---|---|---|
| A | B | C | Y |
| H | H | H | L |
| L | X | X | H |
| X | L | X | H |
| X | X | L | H |

**LOGIC DIAGRAM, EACH GATE (POSITIVE LOGIC)**



## ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

| | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{CC}$ | Supply voltage range | | -0.5 | 4.6 | V |
| $V_I$ | Input voltage range(2) | | -0.5 | 4.6 | V |
| $V_O$ | Output voltage range(2)(3) | | -0.5 | $V_{CC}$ + 0.5 | V |
| $I_{IK}$ | Input clamp current | $V_I$ < 0 | | -50 | mA |
| $I_{OK}$ | Output clamp current | $V_O$ < 0 | | -50 | mA |
| $I_O$ | Continuous output current | | | ±50 | mA |
| | Continuous current through $V_{CC}$ or GND | | | ±100 | mA |
| $\theta_{JA}$ | Package thermal impedance(4) | D package | | 86 | °C/W |
| | | DGV package | | 127 | |
| | | NS package | | 76 | |
| | | PW package | | 113 | |
| $T_{stg}$ | Storage temperature range | | -65 | 150 | °C |

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
(3) This value is limited to 4.6 V maximum.
(4) The package thermal impedance is calculated in accordance with JESD 51-7.

## RECOMMENDED OPERATING CONDITIONS(1)

| | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{CC}$ | Supply voltage | | 1.65 | 3.6 | V |
| $V_{IH}$ | High-level input voltage | $V_{CC}$ = 1.65 V to 1.95 V | 0.65 × $V_{CC}$ | | V |
| | | $V_{CC}$ = 2.3 V to 2.7 V | 1.7 | | |
| | | $V_{CC}$ = 2.7 V to 3.6 V | 2 | | |
| $V_{IL}$ | Low-level input voltage | $V_{CC}$ = 1.65 V to 1.95 V | | 0.35 × $V_{CC}$ | V |
| | | $V_{CC}$ = 2.3 V to 2.7 V | | 0.7 | |
| | | $V_{CC}$ = 2.7 V to 3.6 V | | 0.8 | |
| $V_I$ | Input voltage | | 0 | 3.6 | V |
| $V_O$ | Output voltage | | 0 | $V_{CC}$ | V |
| $I_{OH}$ | High-level output current | $V_{CC}$ = 1.65 V | | -4 | mA |
| | | $V_{CC}$ = 2.3 V | | -12 | |
| | | $V_{CC}$ = 2.7 V | | -12 | |
| | | $V_{CC}$ = 3 V | | -24 | |
| $I_{OL}$ | Low-level output current | $V_{CC}$ = 1.65 V | | 4 | mA |
| | | $V_{CC}$ = 2.3 V | | 12 | |
| | | $V_{CC}$ = 2.7 V | | 12 | |
| | | $V_{CC}$ = 3 V | | 24 | |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | | | 5 | ns/V |
| $T_A$ | Operating free-air temperature | | -40 | 85 | °C |

(1) All unused inputs of the device must be held at $V_{CC}$ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | $V_{CC}$ | MIN | TYP(1) | MAX | UNIT |
|---|---|---|---|---|---|---|
| $V_{OH}$ | $I_{OH}$ = -100 µA | 1.65 V to 3.6 V | $V_{CC}$ - 0.2 | | | V |
| | $I_{OH}$ = -4 mA | 1.65 V | 1.2 | | | |
| | $I_{OH}$ = -6 mA | 2.3 V | 2 | | | |
| | $I_{OH}$ = -12 mA | 2.3 V | 1.7 | | | |
| | | 2.7 V | 2.2 | | | |
| | | 3 V | 2.4 | | | |
| | $I_{OH}$ = -24 mA | 3 V | 2 | | | |
| $V_{OL}$ | $I_{OL}$ = 100 µA | 1.65 V to 3.6 V | | | 0.2 | V |
| | $I_{OL}$ = 4 mA | 1.65 V | | | 0.45 | |
| | $I_{OL}$ = 6 mA | 2.3 V | | | 0.4 | |
| | $I_{OL}$ = 12 mA | 2.3 V | | | 0.7 | |
| | | 2.7 V | | | 0.4 | |
| | $I_{OL}$ = 24 mA | 3 V | | | 0.55 | |
| $I_I$ | $V_I$ = $V_{CC}$ or GND | 3.6 V | | | ±5 | µA |
| $I_{CC}$ | $V_I$ = $V_{CC}$ or GND, $I_O$ = 0 | 3.6 V | | | 10 | µA |
| $\Delta I_{CC}$ | One input at $V_{CC}$ - 0.6 V, Other inputs at $V_{CC}$ or GND | 3 V to 3.6 V | | | 750 | µA |
| $C_i$ | $V_I$ = $V_{CC}$ or GND | 3.3 V | | 4 | | pF |

(1) All typical values are at $V_{CC}$ = 3.3 V, $T_A$ = 25°C.

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

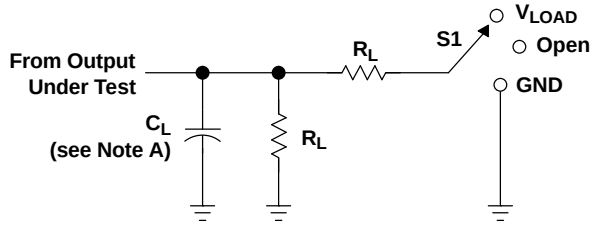
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC}$ = 1.8 V ± 0.15 V | | $V_{CC}$ = 2.5 ± 0.2 V | | $V_{CC}$ = 2.7 V | | $V_{CC}$ = 3.3 V ± 0.3 V | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| $t_{pd}$ | A, B, or C | Y | 1.1 | 4.8 | 1 | 3 | | 3.3 | 1 | 3 | ns |

## OPERATING CHARACTERISTICS

$T_A$ = 25°C

| PARAMETER | | TEST CONDITIONS | $V_{CC}$ = 1.8 V | $V_{CC}$ = 2.5 V | $V_{CC}$ = 3.3 V | UNIT |
|---|---|---|---|---|---|---|
| | | | TYP | TYP | TYP | |
| $C_{pd}$ | Power dissipation capacitance per gate | $C_L$ = 0, f = 10 MHz | 23 | 24 | 26 | pF |

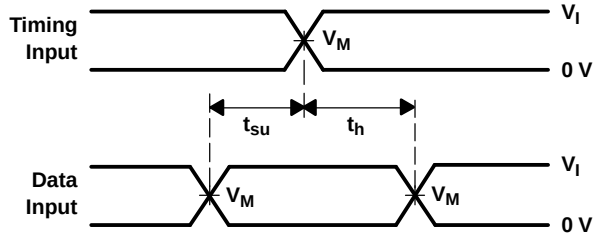
## PARAMETER MEASUREMENT INFORMATION



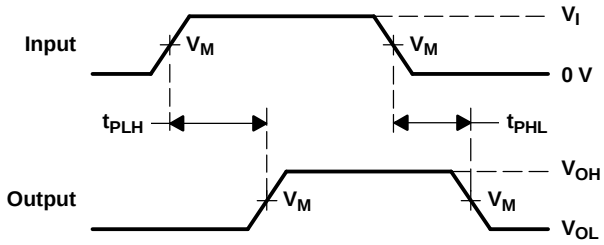

LOAD CIRCUIT

| TEST | S1 |
|---|---|
| $t_{pd}$<br>$t_{PLZ}/t_{PZL}$<br>$t_{PHZ}/t_{PZH}$ | Open<br>$V_{LOAD}$<br>GND |

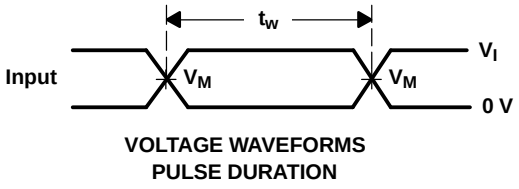
| $V_{CC}$ | INPUT | | $V_M$ | $V_{LOAD}$ | $C_L$ | $R_L$ | $V_\Delta$ |
|---|---|---|---|---|---|---|---|
| | $V_I$ | $t_r/t_f$ | | | | | |
| 1.8 V ± 0.15 V | $V_{CC}$ | ≤2 ns | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 kΩ | 0.15 V |
| 2.5 V ± 0.2 V | $V_{CC}$ | ≤2 ns | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 Ω | 0.15 V |
| 2.7 V | 2.7 V | ≤2.5 ns | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |
| 3.3 V ± 0.3 V | 2.7 V | ≤2.5 ns | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |



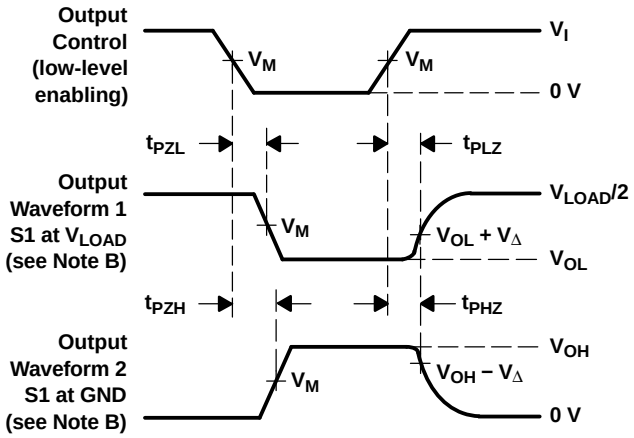

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES




VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES




VOLTAGE WAVEFORMS
PULSE DURATION




VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. $C_L$ includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O$ = 50 Ω.
D. The outputs are measured one at a time, with one transition per measurement.
E. $t_{PLZ}$ and $t_{PHZ}$ are the same as $t_{dis}$.
F. $t_{PZL}$ and $t_{PZH}$ are the same as $t_{en}$.
G. $t_{PLH}$ and $t_{PHL}$ are the same as $t_{pd}$.
H. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74ALVC10D | ACTIVE | SOIC | D | 14 | 50 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ALVC10 | Samples |
| SN74ALVC10DGVR | ACTIVE | TVSOP | DGV | 14 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | VA10 | Samples |
| SN74ALVC10DR | ACTIVE | SOIC | D | 14 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ALVC10 | Samples |
| SN74ALVC10NSR | ACTIVE | SO | NS | 14 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ALVC10 | Samples |
| SN74ALVC10PWR | ACTIVE | TSSOP | PW | 14 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | VA10 | Samples |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

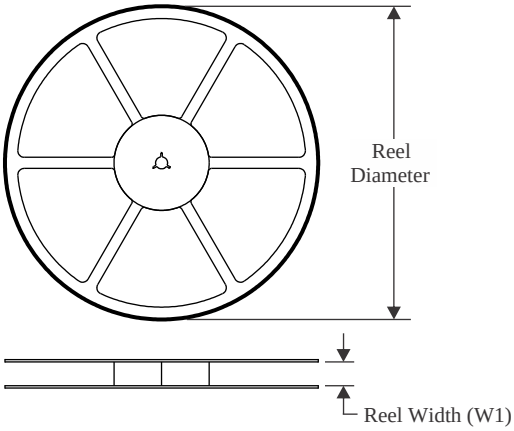
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

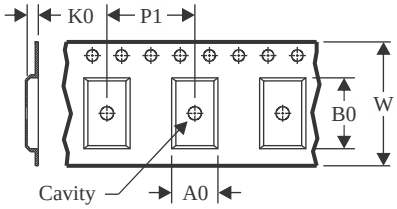
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

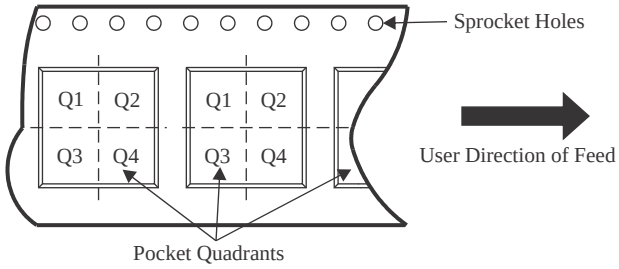



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

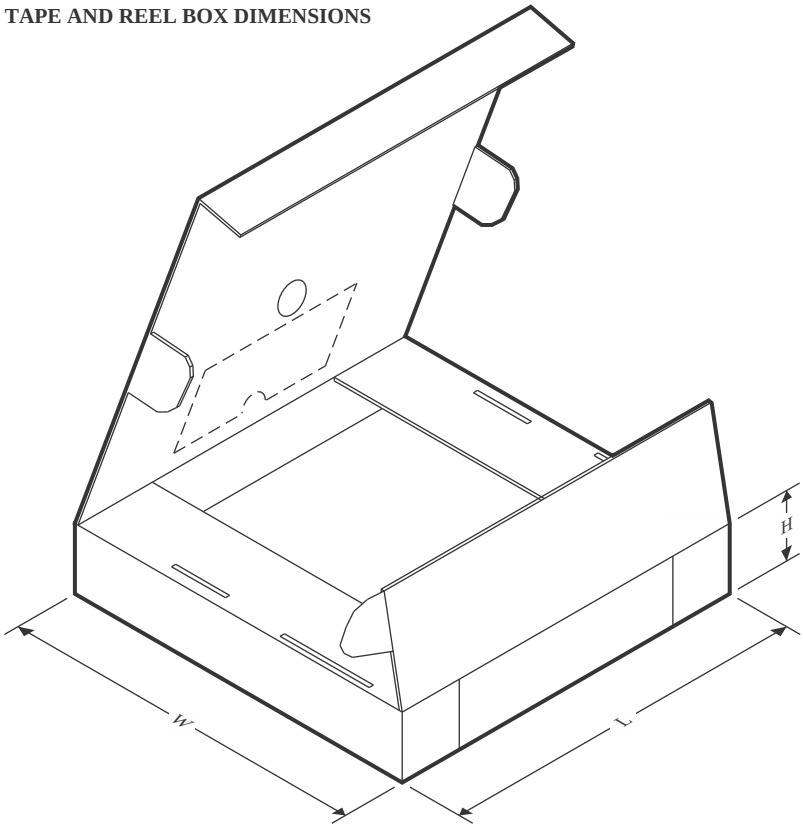
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74ALVC10DGVR | TVSOP | DGV | 14 | 2000 | 330.0 | 12.4 | 6.8 | 4.0 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74ALVC10DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74ALVC10NSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74ALVC10PWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

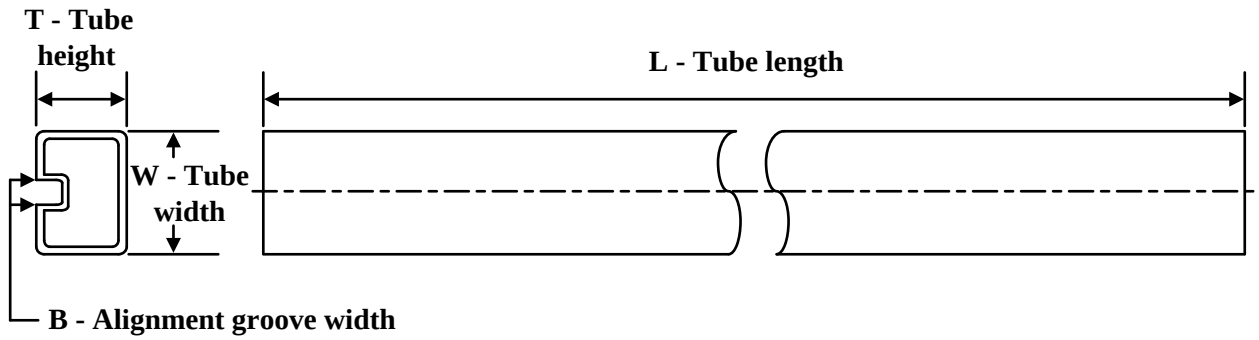
TAPE AND REEL BOX DIMENSIONS




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| SN74ALVC10DGVR | TVSOP | DGV | 14 | 2000 | 356.0 | 356.0 | 35.0 |
| SN74ALVC10DR | SOIC | D | 14 | 2500 | 356.0 | 356.0 | 35.0 |
| SN74ALVC10NSR | SO | NS | 14 | 2000 | 356.0 | 356.0 | 35.0 |
| SN74ALVC10PWR | TSSOP | PW | 14 | 2000 | 356.0 | 356.0 | 35.0 |

## TUBE




*All dimensions are nominal

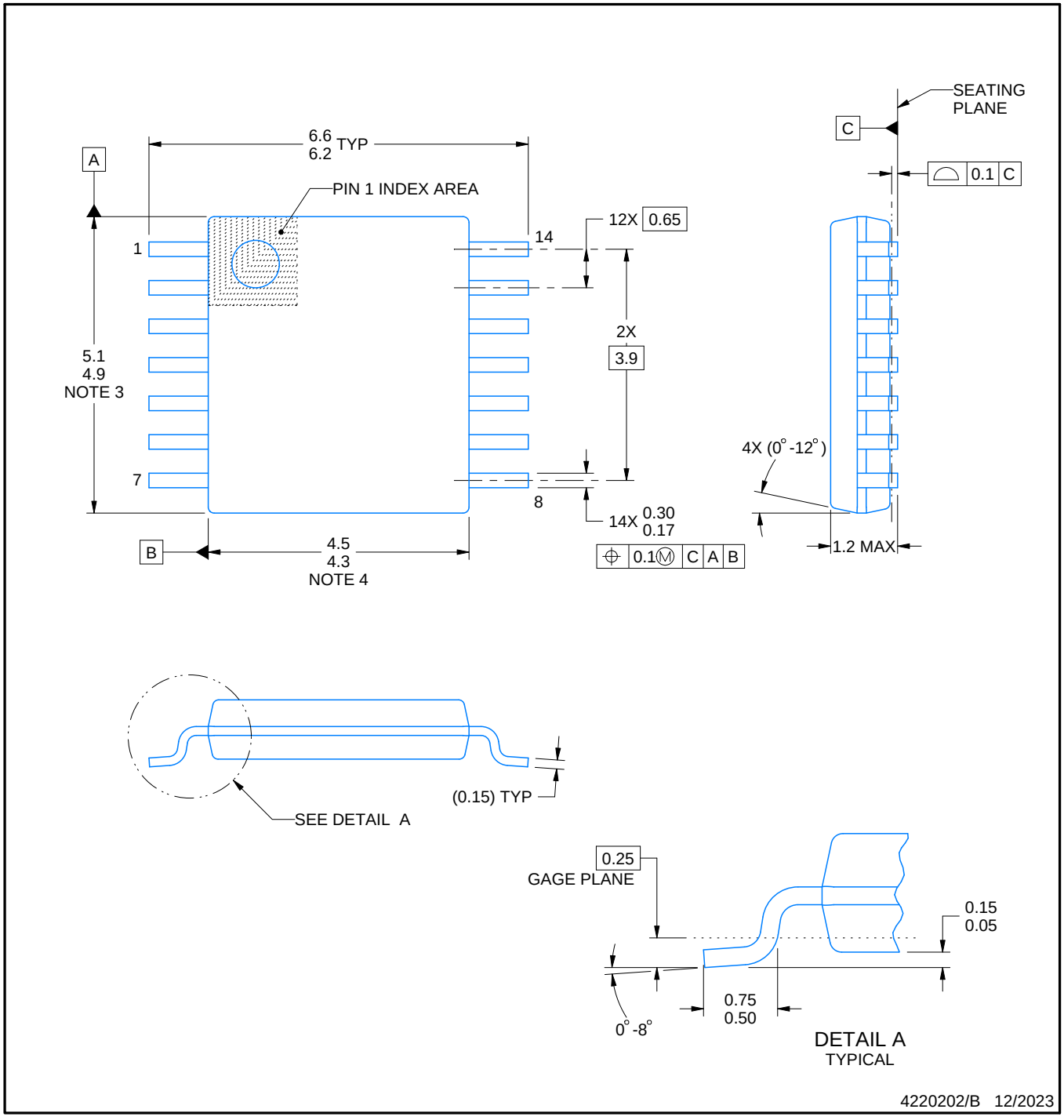
| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|---|---|---|---|---|---|---|---|---|
| SN74ALVC10D | D | SOIC | 14 | 50 | 506.6 | 8 | 3940 | 4.32 |

# PACKAGE OUTLINE

## PW0014A

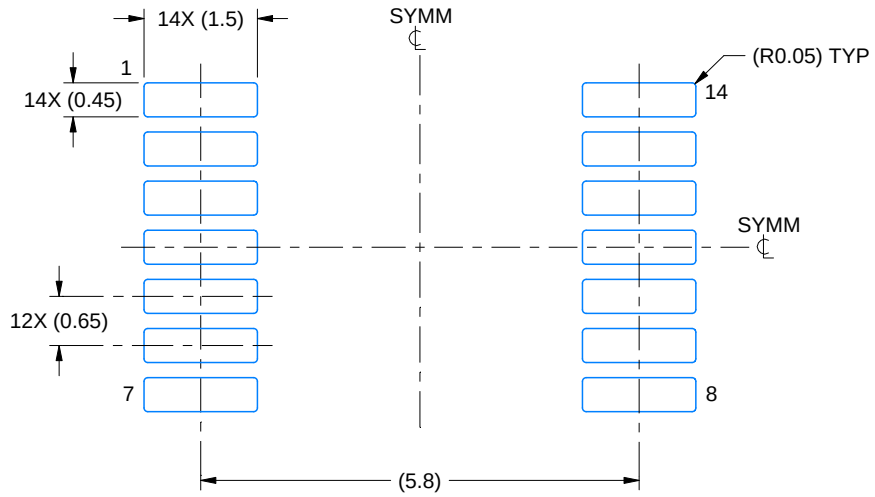
## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

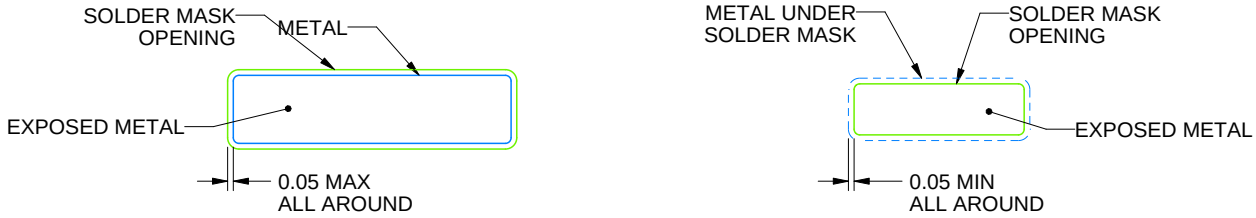



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.




LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

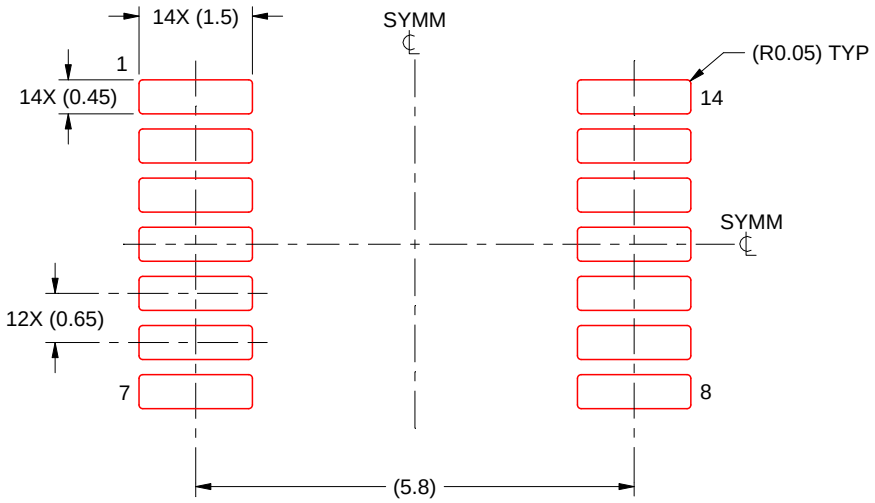



SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

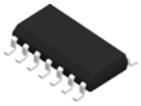



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

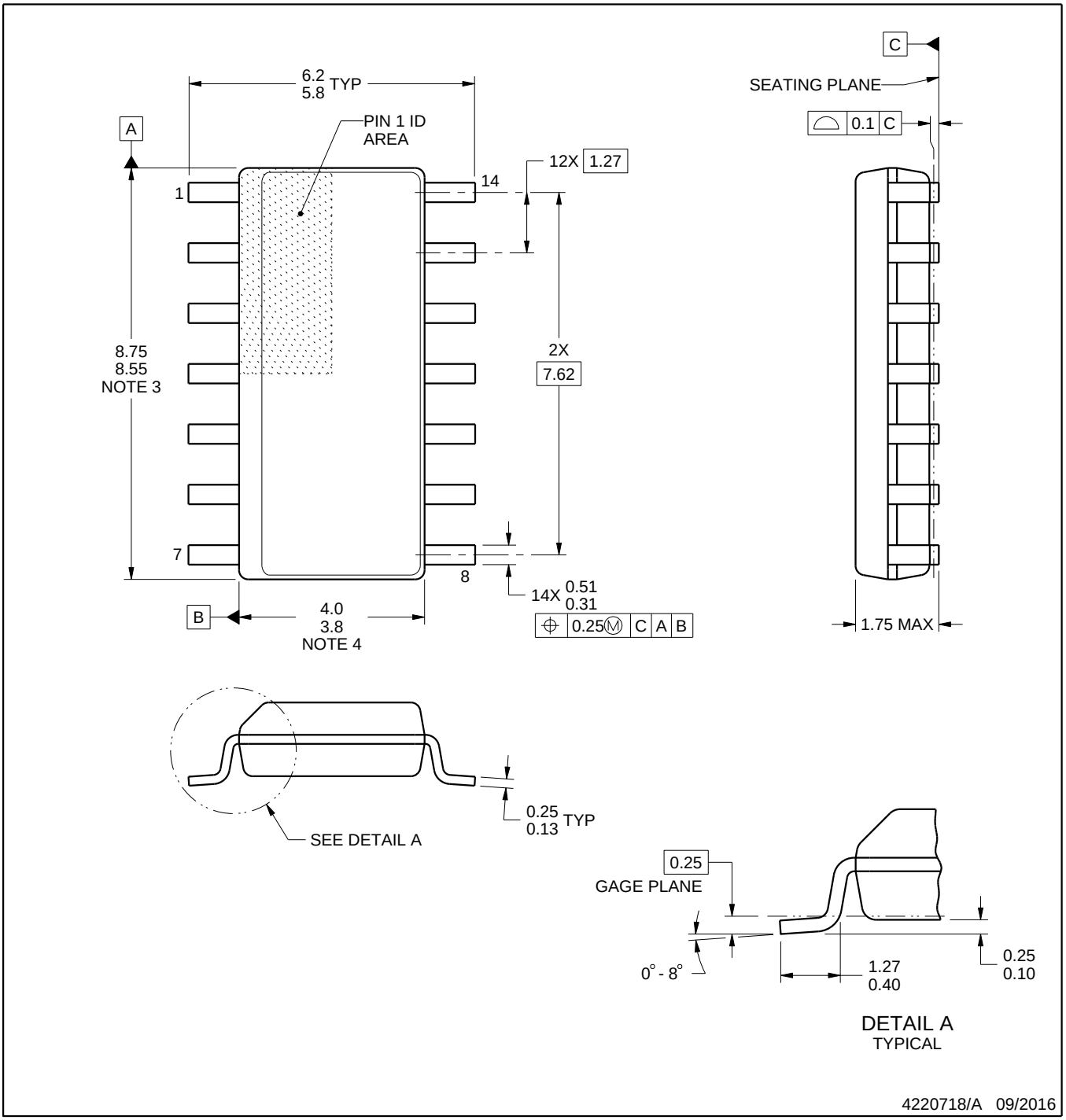


# PACKAGE OUTLINE

## D0014A

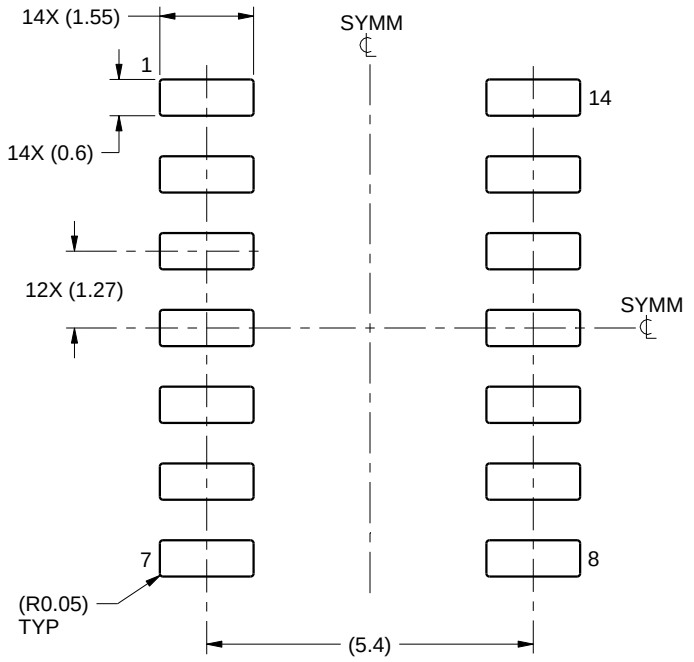
## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

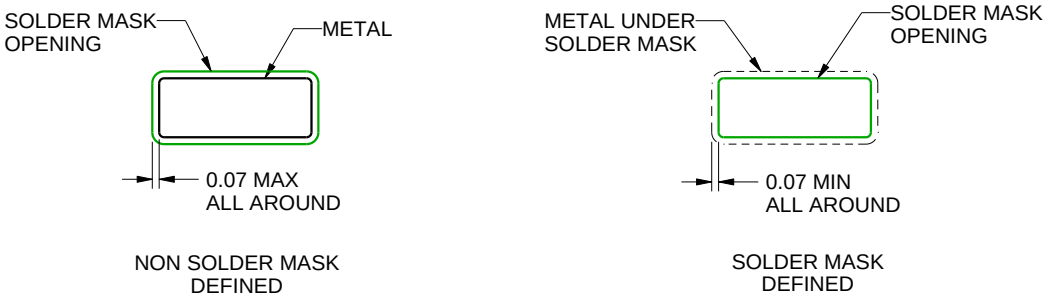



NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.




LAND PATTERN EXAMPLE
SCALE:8X




SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

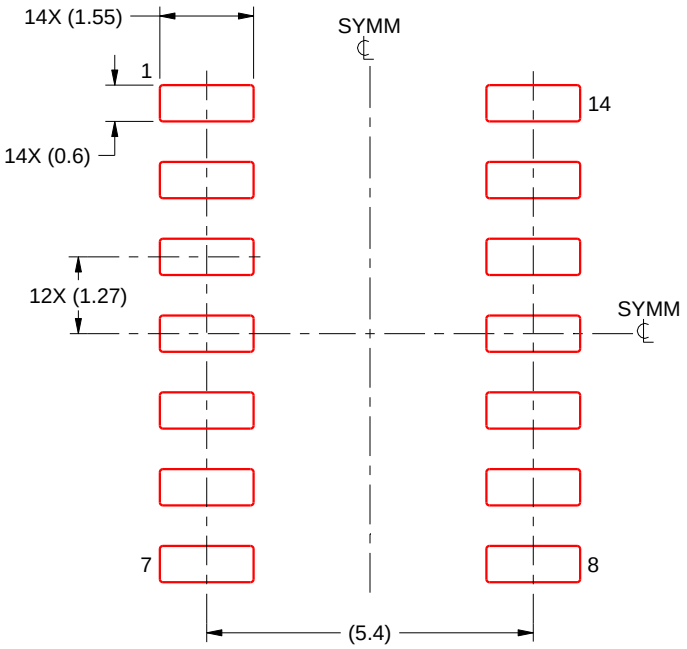
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

## D0014A

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT




SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

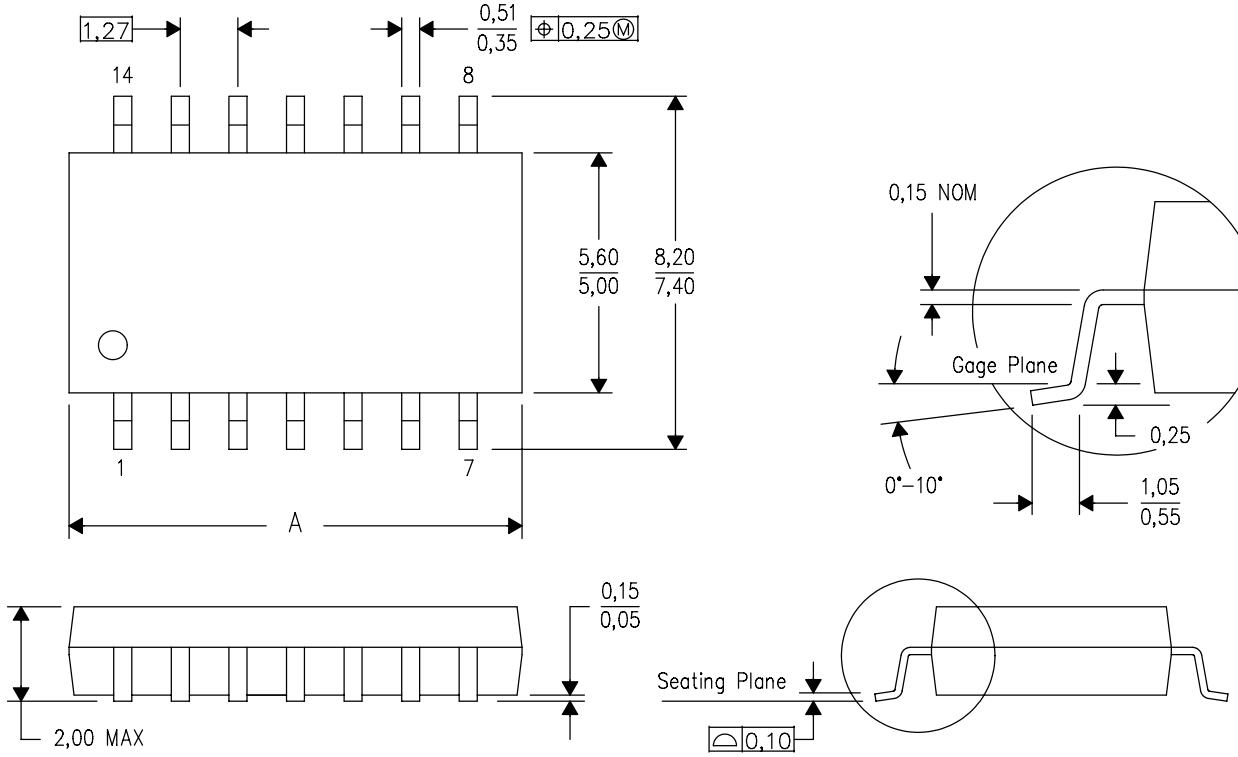
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## MECHANICAL DATA

**NS (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**



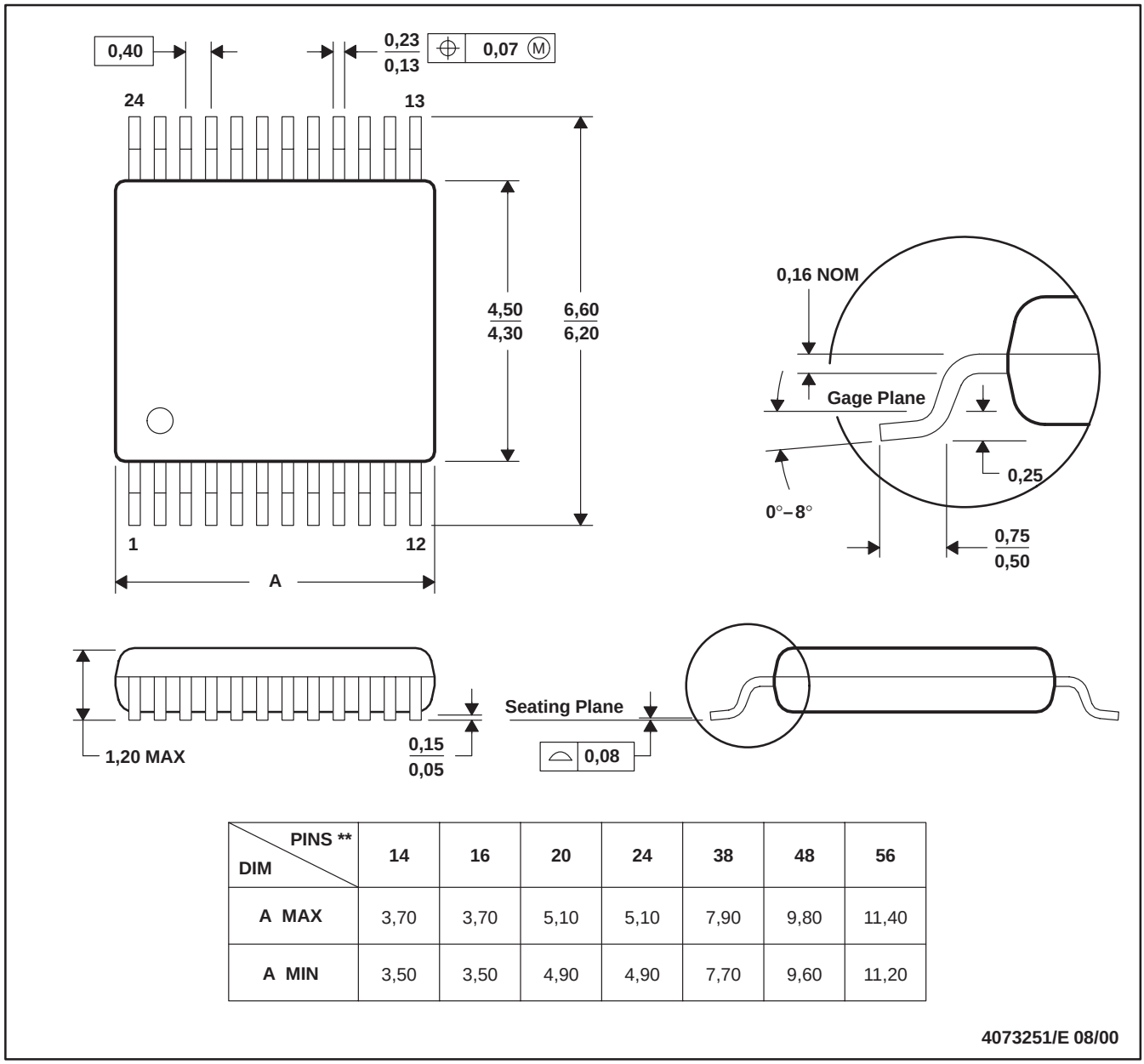

| DIM \ PINS ** | 14 | 16 | 20 | 24 |
|---|---|---|---|---|
| A MAX | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN | 9,90 | 9,90 | 12,30 | 14,70 |

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

**DGV (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE**

**24 PINS SHOWN**




| DIM \ PINS ** | 14 | 16 | 20 | 24 | 38 | 48 | 56 |
|---|---|---|---|---|---|---|---|
| A MAX | 3,70 | 3,70 | 5,10 | 5,10 | 7,90 | 9,80 | 11,40 |
| A MIN | 3,50 | 3,50 | 4,90 | 4,90 | 7,70 | 9,60 | 11,20 |

**4073251/E 08/00**

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265